IEEE P802.3ck Ad Hoc meeting –

June 12, 2019

Prepared by Kent Lusted and Beth Kochuparambil

Proposed Agenda:

- Approval of the Agenda
- Approve 8 May 2019 ad hoc minutes
- IEEE Patent Policy reminder:
  - http://www.ieee802.org/3/patent.html
- IEEE Participation Requirements reminder
- Logistics for May Interim meeting
- Status of the Task Force
- .3ck Ad Hoc –
  - "On-die Termination Model for COM", Adam Healey
  - "COM 2.70 Update", Rich Mellitz
  - "Dual FEC Option", Mark Gustlin

Presentations posted at: http://www.ieee802.org/3/ck/public/adhoc/index.html

Meeting began at ~7:00 a.m. Pacific by Beth Kochuparambil.

Meeting began with the agenda presentation:
http://www.ieee802.org/3/ck/public/adhoc/jun12_19/agenda_061219_3ck_adhoc.pdf

The ad hoc chair reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes. Reminded participants to mute lines when not speaking and reviewed the steps to unmute.

Showed the links to the IEEE P802.3ck Task Force ad hoc page and the email reflector.

Presented the proposed agenda. There was no opposition. The agenda was approved by the ad hoc.

Reminded participants of the IEEE Participation Requirements and showed the slide with the Participation requirements. She asked if anyone was unfamiliar with the IEEE Participation Requirements. No one responded.

Chair noted that the May 8, 2019 minutes were posted. She asked if there were corrections or modifications. No one responded. Minutes were approved by the Task Force.

Reminded participants of the IEEE patent policy. She asked if anyone was unfamiliar with the IEEE patent policy. No one responded.

Agenda Items

P802.3ck Update, Beth Kochuparambil
See: http://www.ieee802.org/3/ck/public/adhoc/jun12_19/agenda_061219_3ck_adhoc.pdf

- Task Force will meet week of July 15, 2019 in Vienna, Austria. Meeting Tuesday-Thursday.
- Request for presentations due Friday, July 5, 2019 AOE.
- Presentations are due Wednesday, July 10, 2019 at 5pm Pacific.
- Goal: adopt baselines and prepare for draft 1.0.

Presentation #1:
"On-die Termination Model for COM", Adam Healey
See: http://www.ieee802.org/3/ck/public/adhoc/jun12_19/healey_3ck_adhoc_01_061219.pdf

- Discussed the amount of bandwidth improvement with the proposed termination model.
- Discussed the difference between the improved termination model vs. a big reduction in Cd.

Presentation #2:
"COM 2.70 Update", Rich Mellitz
See: http://www.ieee802.org/3/ck/public/adhoc/jun12_19/mellitz_3ck_adhoc_01_061219.pdf

- The updated version of COM is posted at http://www.ieee802.org/3/ck/public/tools/index.html
- On slide 6, there was an error with the Z_p RX value.

Presentation #3:
"Dual FEC Option", Mark Gustlin
See: http://www.ieee802.org/3/ck/public/adhoc/jun12_19/gustlin_3ck_adhoc_01_061219.pdf

- The current proposal recommends that both directions have the same FEC mode based on offline feedback.
- It was noted that the proposal requires devices to mandatorily support both FEC modes in the TX path.
- Discussed the impact to a CDR in the path.

The ad hoc meeting ended at ~8:10 a.m. Pacific.

List of attendees (captured from Webex tool)

Name	Affiliation	Employed by
Adam Healey	Broadcom	Broadcom
Adrian Butter	Global Foundries	Global Foundries
Alan Kinningham	I-PEX	I-PEX
Alex Levin	Microsoft	Microsoft
Ali Ghiasi	Ghiasi Quantum	Ghiasi Quantum
Andy Zambell	Amphenol	Amphenol
Beth Kochuparambil	Cisco	Cisco
Bill Kirkland	Semtech	Semtech
Brandon Gore	Samtec	Samtec
Burrell Best	Samtec	Samtec
Cathy Huang	Huawei	Huawei
Chien-Ping Kao	Intel	Intel
Chris DiMinico	PHY-SI	PHY-SI
Clint Walker	Alphawave IP	Alphawave IP
Cristian Filip	Mentor	Mentor
David Malicoat	Senko	Malicoat Networking Solutions
David Rennie	Synopsys	Synopsys
Ed Frlan	Semtech	Semtech
Erdem Matoglu	Amphenol	Amphenol
Frank Chang	Inphi	Inphi

Gary Nicholl	Cisco	Cisco
Geoff Zhang	Xilinx	Xilinx
Greg McSorley	Amphenol	Amphenol
guangcan	Huawei	Huawei
Harisankar Aravindakshan	Cadence	Cadence
Hormoz Djahanshahi	Microsemi	Microsemi
Howard Heck	Intel	Intel
Hsinho Wu	Intel	Intel
Ilya Lyubumirshky	Inphi	Inphi
Inho Kim	Marvell	Marvell
Jane Lim	Cisco	Cisco
Jeff Slavick	Broadcom	Broadcom
John D'Ambrosia	Futurewei (US Subsidiary of Huawei)	Futurewei
John Ewen	Globalfoundries	Globalfoundries
Jon Beecroft	Cray	Cray
Juan Martinez	IBM	IBM
Kapil Shrikhande	Innovium	Innovium
Kent Lusted	Intel	Intel
Kumaran Krishnasamy	Broadcom	Broadcom
Mark Gustlin	Cisco	Cisco
Mark Kimber	Samtech	Samtech
Masashi Shimanouchi	Intel	Intel

Matt Brown	Macom	Macom
Mau-Lin Wu	Mediatek	Mediatek
Mike Dudek	Cavium	Cavium
Mike Klempa	UNH-IOL	UNH-IOL
Nathan Tracy	TE Connectivity	TE Connectivity
Nikolay Ledentsov	VI Systems	VI Systems
Pete Anslow	Ciena	Ciena
Phil Sun	Credo	Credo
Piers Dawe	Mellanox	Mellanox
Pirooz Tooyserkani	Cisco	Cisco
Rich Mellitz	Samtec	Samtec
Rick Rabinovich	Keysight	Keysight
Rita Horner	Synopsys	Synopsys
Sam Kocsis	Amphenol	Amphenol
Sara Zebian	Google	Google
Scott Sommers	Molex	Molex
Shawn Nicholl	Xilinx	Xilinx
Shimon Muller	Axalume	Axalume
Stephen Hamblin (Spectra7)	Spectra7	Spectra7
Tao Hu	Marvell	Marvell
Ted Sprague	Infinera	Infinera
Tom Palkert	Molex/Macom	Molex/Macom
Upen Kareti	Cisco	Cisco

Wendy Wu	Cadence	Cadence
Xiang He	Huawei	Huawei
Yan Zhuang	Huawei	Huawei
Yasuo Hidaka	Credo	Credo
Yuchun(Louis) Lu	Huawei	Huawei
Zhiwei Yang	ZTE	ZTE
Zvi Rechtman	Mellanox	Mellanox